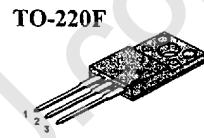


Advanced Power MOSFET**SSS6N80A****FEATURES**

- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Lower Leakage Current : 25 μ A (Max.) @ $V_{DS} = 800V$
- Low $R_{DS(ON)}$: 1.472 Ω (Typ.)

$BV_{DSS} = 800\text{ V}$
 $R_{DS(on)} = 2.0\ \Omega$
 $I_D = 3.5\text{ A}$



1.Gate 2. Drain 3. Source

Absolute Maximum Ratings

Symbol	Characteristic	Value	Units
V_{DSS}	Drain-to-Source Voltage	800	V
I_D	Continuous Drain Current ($T_c=25\text{ }^\circ\text{C}$)	3.5	A
	Continuous Drain Current ($T_c=100\text{ }^\circ\text{C}$)	2.2	
I_{DM}	Drain Current-Pulsed ①	24	A
V_{GS}	Gate-to-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy ②	457	mJ
I_{AR}	Avalanche Current ①	3.5	A
E_{AR}	Repetitive Avalanche Energy ①	5	mJ
dv/dt	Peak Diode Recovery dv/dt ③	2.0	V/ns
P_D	Total Power Dissipation ($T_c=25\text{ }^\circ\text{C}$)	50	W
	Linear Derating Factor	0.4	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating Junction and Storage Temperature Range	- 55 to + 150	$^\circ\text{C}$
	Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5-seconds	300	

Thermal Resistance

Symbol	Characteristic	Typ.	Max.	Units
$R_{\theta_{JC}}$	Junction-to-Case		2.5	$^\circ\text{C/W}$
	Junction-to-Ambient	—	62.5	



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Electrical Characteristics ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
BV_{DSS}	Drain-Source Breakdown Voltage	800	--	--	V	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\mu\text{A}$
$\Delta \text{BV}/\Delta T_J$	Breakdown Voltage Temp. Coeff.	--	0.93	--	V/ $^\circ\text{C}$	$\text{I}_D=250\mu\text{A}$ See Fig 7
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	2.0	--	3.5	V	$\text{V}_{\text{DS}}=5\text{V}, \text{I}_D=250\mu\text{A}$
I_{GSS}	Gate-Source Leakage, Forward	--	--	100	nA	$\text{V}_{\text{GS}}=30\text{V}$
	Gate-Source Leakage, Reverse	--	--	-100		$\text{V}_{\text{GS}}=-30\text{V}$
I_{DSS}	Drain-to-Source Leakage Current	--	--	25	μA	$\text{V}_{\text{DS}}=800\text{V}$
		--	--	250		$\text{V}_{\text{DS}}=640\text{V}, \text{T}_C=125^\circ\text{C}$
$\text{R}_{\text{DS(on)}}$	Static Drain-Source On-State Resistance	--	--	2.0	Ω	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=0.85\text{A}$ ④*
g_{fs}	Forward Transconductance	--	3.23	--	mS	$\text{V}_{\text{DS}}=50\text{V}, \text{I}_D=0.85\text{A}$ ④
C_{iss}	Input Capacitance	--	1500	1950	pF	$\text{V}_{\text{GS}}=0\text{V}, \text{V}_{\text{DS}}=25\text{V}, f=1\text{MHz}$ See Fig 5
C_{oss}	Output Capacitance	--	140	165		
C_{rss}	Reverse Transfer Capacitance	--	57	66		
$t_{\text{d(on)}}$	Turn-On Delay Time	--	23	55	ns	$\text{V}_{\text{DD}}=400\text{V}, \text{I}_D=2\text{A},$ $\text{R}_G=16\Omega$ See Fig 13 ④ ⑤
t_r	Rise Time	--	40	90		
$t_{\text{d(off)}}$	Turn-Off Delay Time	--	92	195		
t_f	Fall Time	--	34	80		
Q_g	Total Gate Charge	--	67	88	nC	$\text{V}_{\text{DS}}=640\text{V}, \text{V}_{\text{GS}}=10\text{V},$ $\text{I}_D=2\text{A}$ See Fig 6 & Fig 12 ④ ⑤
Q_{gs}	Gate-Source Charge	--	11.2	--		
Q_{gd}	Gate-Drain("Miller") Charge	--	29.6	--		

Source-Drain Diode Ratings and Characteristics

Symbol	Characteristic	Min.	Typ.	Max.	Units	Test Condition
I_s	Continuous Source Current	--	--	3.5	A	Integral reverse pn-diode in the MOSFET
I_{SM}	Pulsed-Source Current ①	--	--	24		
V_{SD}	Diode Forward Voltage ④	--	--	1.4	V	$\text{T}_J=25^\circ\text{C}, \text{I}_s=3.5\text{A}, \text{V}_{\text{GS}}=0\text{V}$
t_{π}	Reverse Recovery Time	--	520	--	ns	$\text{T}_J=25^\circ\text{C}, \text{I}_F=\infty\text{A}$ $d\text{I}/dt=100\text{A}/\mu\text{s}$ ④
Q_{π}	Reverse Recovery Charge	--	6.66	--	μC	

Notes :

- Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- $L=70\text{mH}, \text{I}_{\text{AS}}=3.5\text{A}, \text{V}_{\text{DD}}=50\text{V}, \text{R}_c=27\Omega$, Starting $\text{T}_J=25^\circ\text{C}$
- $\text{I}_{\text{SD}} \leq 7\text{A}, d\text{I}/dt \leq 150\text{A}/\mu\text{s}, \text{V}_{\text{DD}} \leq \text{BV}_{\text{DSS}}$, Starting $\text{T}_J=25^\circ\text{C}$
- Pulse Test : Pulse Width = $250\mu\text{s}$, Duty Cycle $\leq 2\%$
- Essentially Independent of Operating Temperature

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Fig 1. Output Characteristics

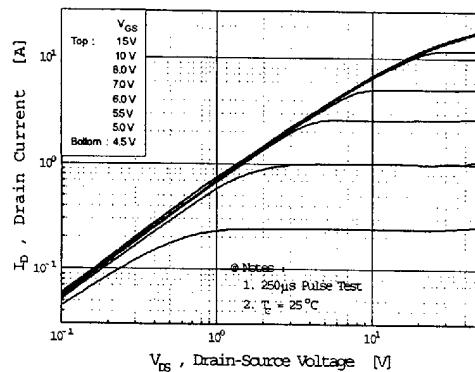


Fig 2. Transfer Characteristics

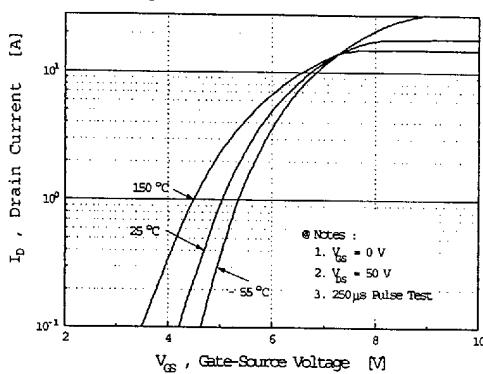


Fig 3. On-Resistance vs. Drain Current

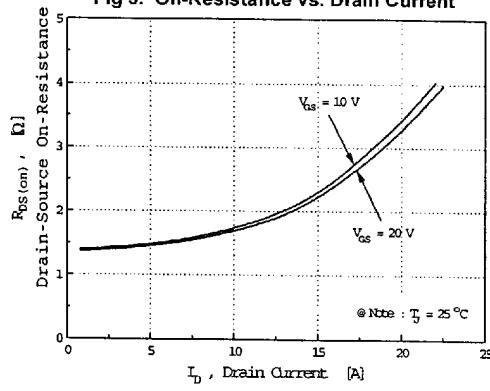


Fig 4. Source-Drain Diode Forward Voltage

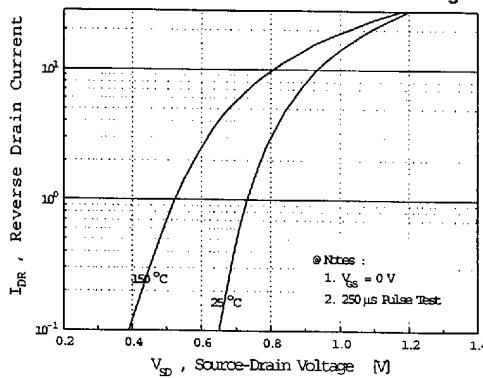


Fig 5. Capacitance vs. Drain-Source Voltage

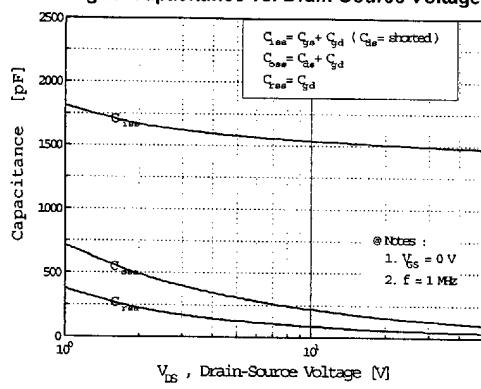
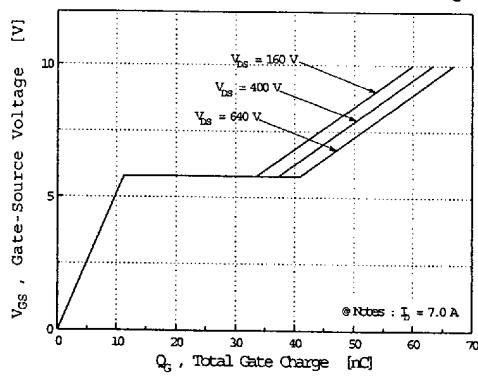
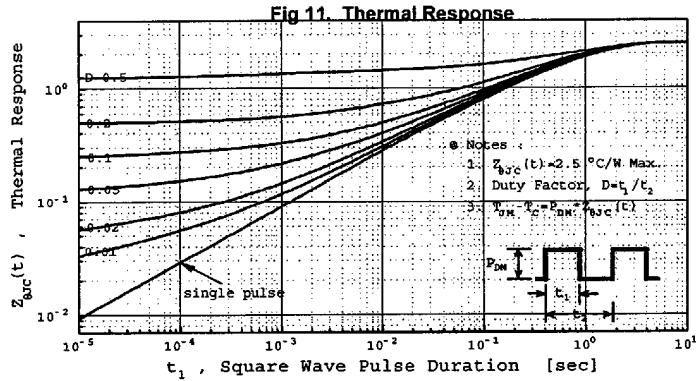
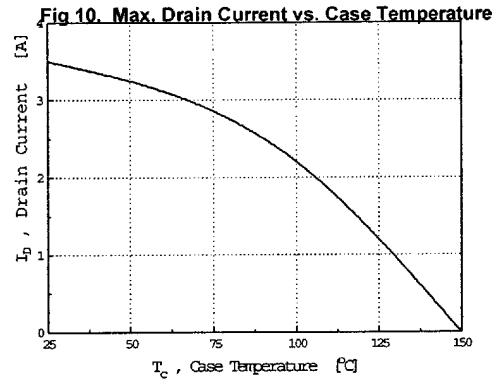
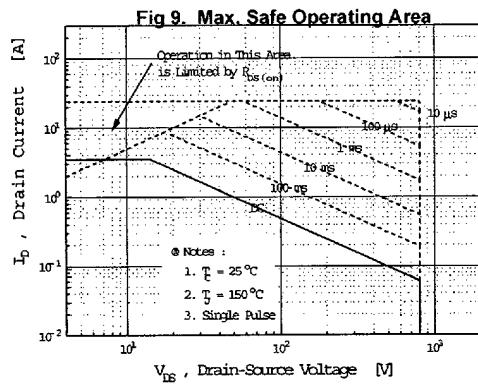
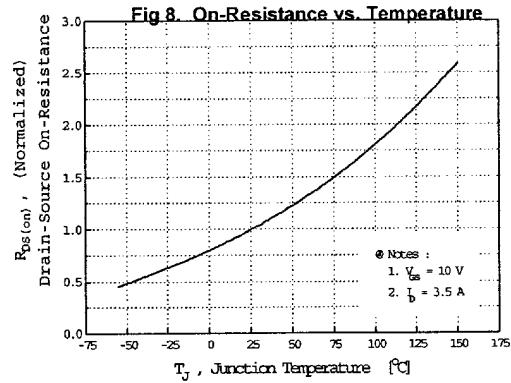
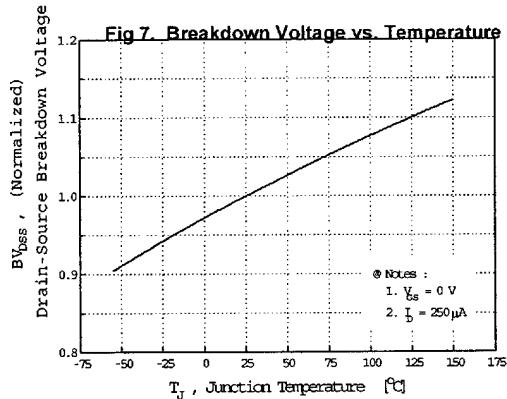


Fig 6. Gate Charge vs. Gate-Source Voltage



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Fig 12. Gate Charge Test Circuit & Waveform

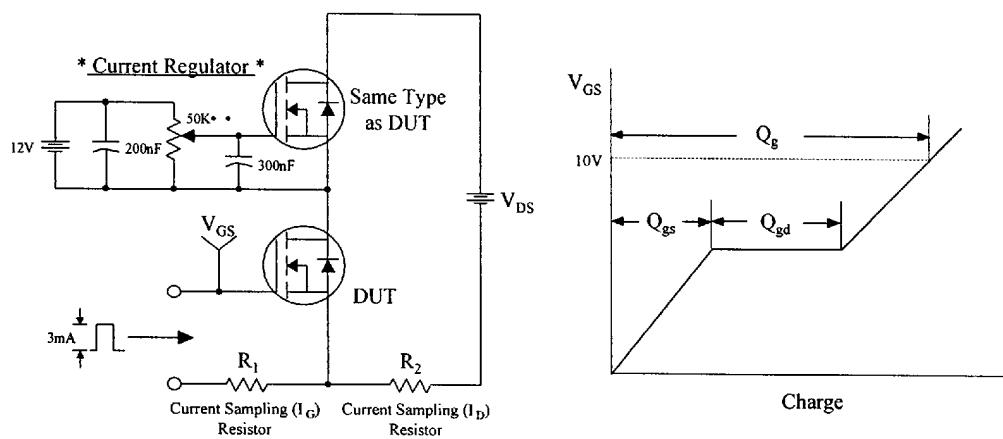


Fig 13. Resistive Switching Test Circuit & Waveforms

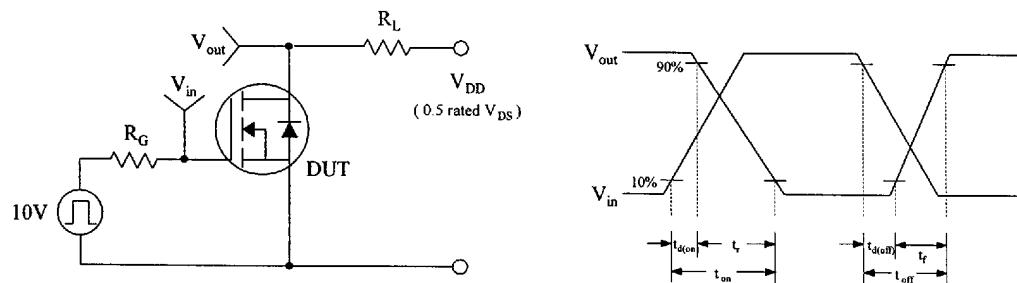
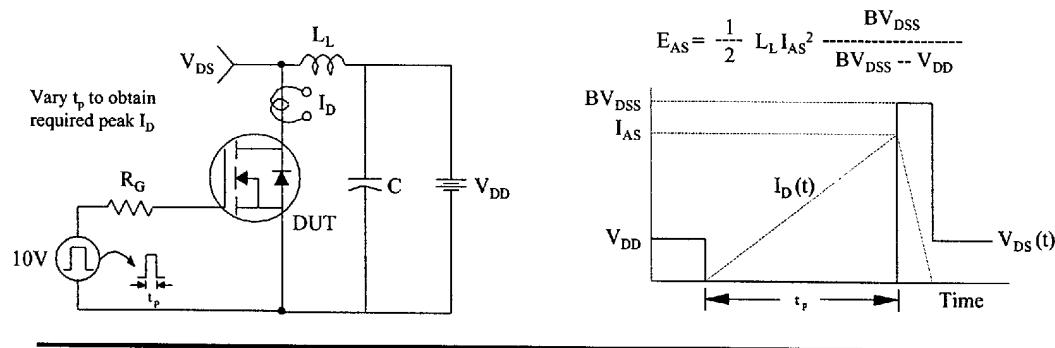


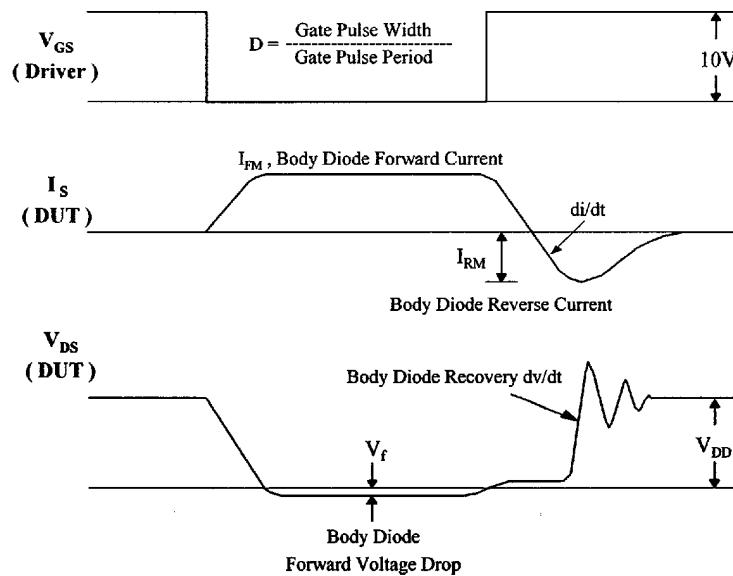
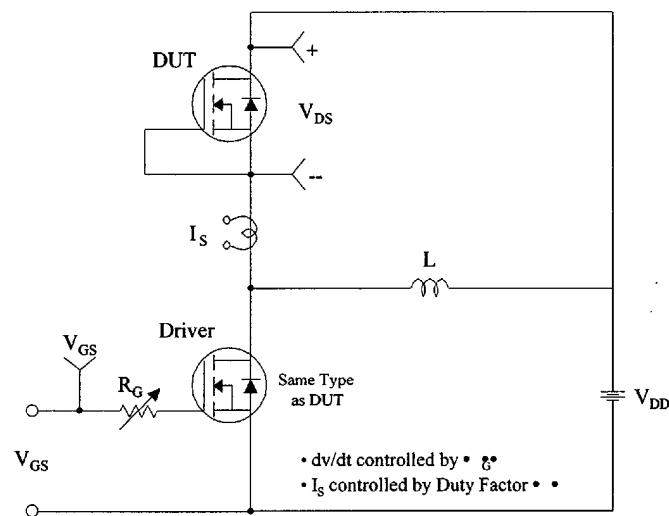
Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms



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Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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